

KYOCERA KE-520TD-2

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Achieved Fast Cure for In-Line Process as well as Excellent Fillings and Applicable from Insertion Type to Surface Mount Type.

Strong Points

Achieve Good and Necessary Filling in KE-520Series to Apply to Ultra Small Packages.

JEDEC level 1 is Possible in Ultra Small Packages.

Good Adhesion Strength Even after High Temperature Reflow Soldering Process.

Fast Cure Enabling High Productive In-Line Auto Process.

Excellent moldability and show improvement in moldability yield.

Application

Surface Mount Device

TO-92 Type (Insertion Type)

Ultrasmall PKG

General Information		
Features	Fast Cure	
	Good Adhesion	
	Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	1.90	g/cm³
Spiral Flow	100	cm
Thermal	Nominal Value	Unit
Glass Transition Temperature	175	°C
CLTE - Flow		
-- 1	1.5E-5	cm/cm/°C
-- 2	6.0E-5	cm/cm/°C
Uncured Properties	Nominal Value	Unit
Gel Time	0.33	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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